

Type number	Package	Package description	Total product weight
74HCT2G00DC	SOT765-1	VSSOP8	9.98163 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935274813125	10	1	260	30 s	1	240	20 s	3	Ayutthaya, Thailand; Suzhou, China; Bangkok, Thailand; Nijmegen, Netherlands	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Filler	Silver (Ag)	7440-22-4	0.02871	80.10000	0.28761
	Polymer	Resin system	Proprietary	0.00713	19.90000	0.07145
		subTotal		0.03584	100.00000	0.35906
Die	Doped silicon	Silicon (Si)	7440-21-3	0.13079	100.00000	1.31035
		subTotal		0.13079	100.00000	1.31035
Lead Frame Material	Copper alloy	Copper (Cu)	7440-50-8	3.39855	97.00000	34.04805
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.10511	3.00000	1.05303
		subTotal		3.50366	100.00000	35.10108
Mould Compound	Additive	Non hazardous	Proprietary	0.29057	4.70000	2.91103
	Filler	Silica fused	60676-86-0	4.88402	79.00000	48.93005
	Flame retardant	Magnesium Hydroxide (Mg(OH)2)	1309-42-8	0.37094	6.00000	3.71621
	Pigment	Carbon black	1333-86-4	0.01236	0.20000	0.12387
	Polymer	1,4-bis(methoxymethyl)benzene/phenol copolymer	26834-02-6	0.24729	4.00000	2.47747
		Non hazardous	Proprietary	0.25347	4.10000	2.53941
		Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.12365	2.00000	1.23874
	subTotal		6.18230	100.00000	61.93678	
Pre-Plating	Pure metal layer	Gold (Au)	7440-57-5	0.00309	3.00000	0.03094
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.09502	92.30000	0.95198
		Palladium (Pd)	7440-05-3	0.00319	3.10000	0.03197
		Silver (Ag)	7440-22-4	0.00165	1.60000	0.01650
		subTotal		0.10295	100.00000	1.03139
Wire	Pure metal	Copper (Cu)	7440-50-8	0.02608	100.00000	0.26133
		subTotal		0.02608	100.00000	0.26133

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